

# Open Domain-Specific Architecture

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## ODSA: Open Domain-Specific Architecture

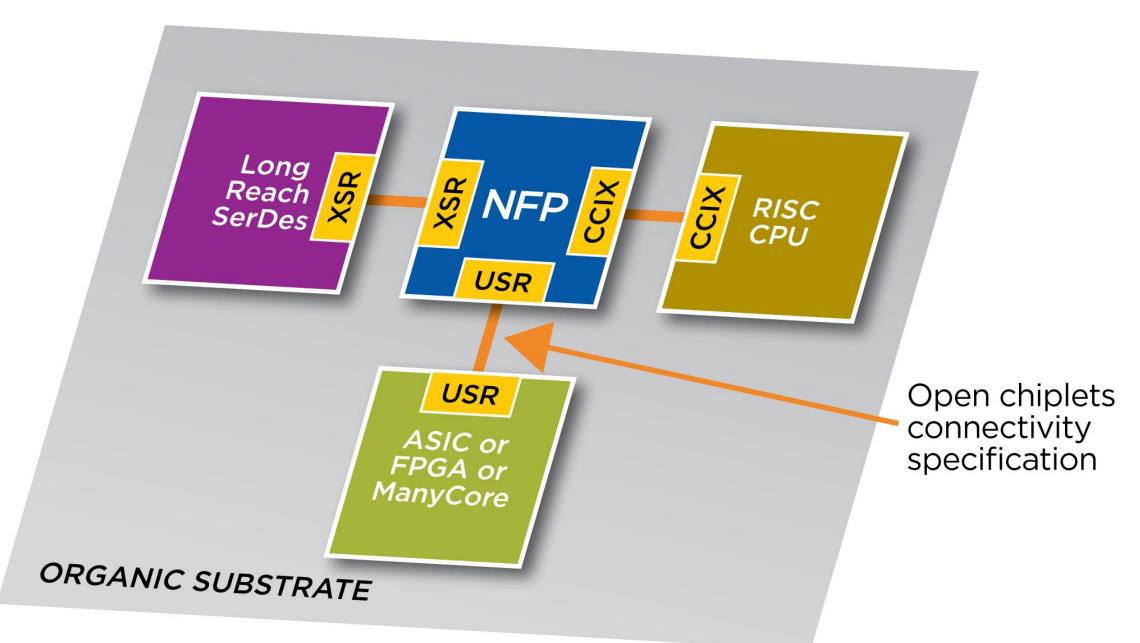
Domain-specific architecture: Programmable devices optimized for specific applications or class of applications. Meet the demands of high-intensity workloads in the data center and at the edge – e.g. machine learning, video processing

Chiplets: Implement an integrated product as a <u>collection</u> of die in a single package, instead of a single die. Each die is a chiplet. Can reduce development and manufacturing costs.



## The Open Domain-Specific Architecture

An open interface for interchiplet communication



aggregation Stack Jie disaggregation Stack Cache Non-ISF Coherent Coherent Tile Link SATA Routing PCIe Link Inter-Chiplet Intra-Chiplet Package ( Link Layer Link Layer Layer PIPE Interface Adapter **Common Abstraction** SerDes Parallel PCle BoW XSR, Kandou, AIB, HBM,... Organic substrate Interposers/bridges Inter-chiplet PHY and packaging options

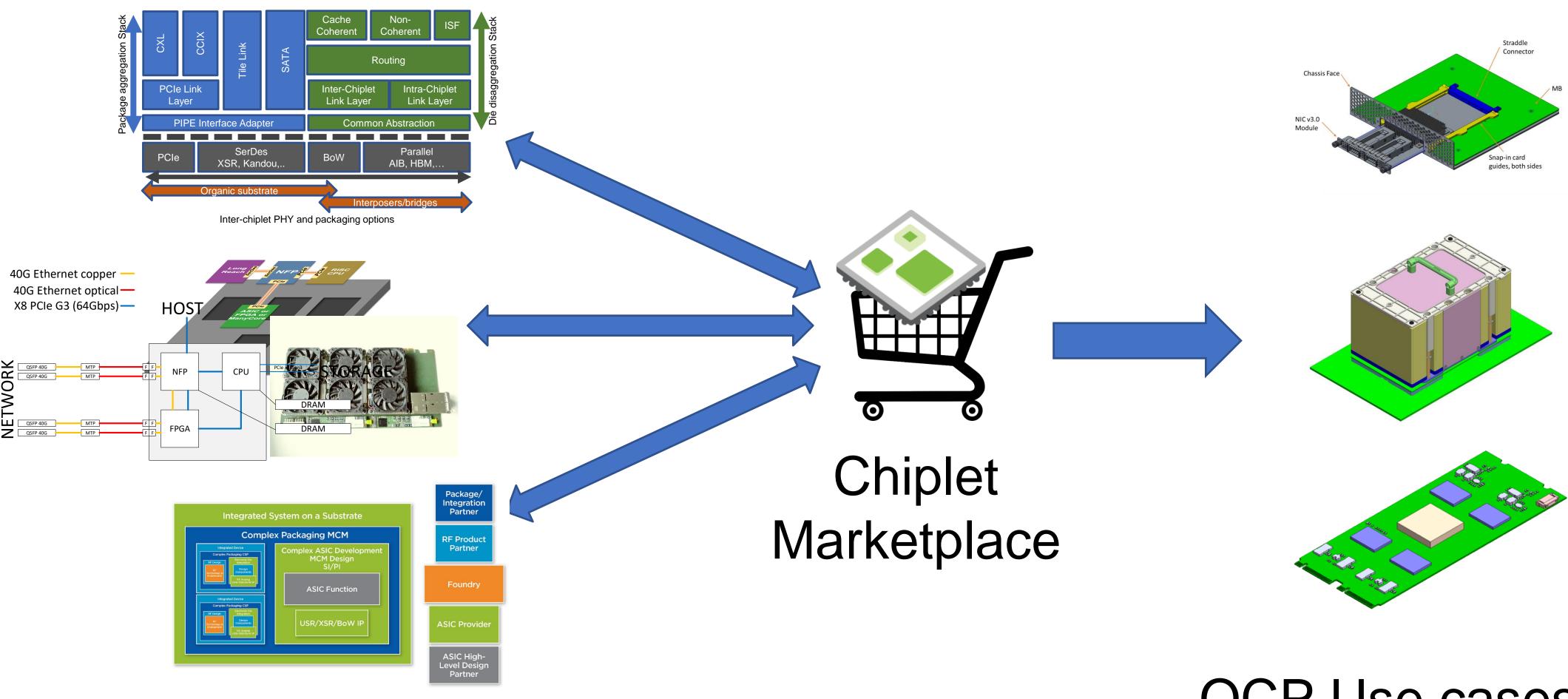
#### **Chiplets for accelerators:**

- Shrink a board into a package
- Disaggregate a complex or large die

Multiple chiplets need to function as though they are on one die



### ODSA Goal: Chiplet Marketplace



**ODSA** Activities

OCP Use cases



## ODSA Announcements at the Regional Summit

All activities involve broad and active participation from multiple members

OCP: Significant progress and growth in the ODSA

Avera: Releasing a 0.7 draft proposal for a Bunch of Wires (BoW) interface – at <a href="https://www.opencompute.org/wiki/Server/ODSA">https://www.opencompute.org/wiki/Server/ODSA</a>

Achronix: A design for the proof-of-concept software development platform and a mock up (go see it)

zGlue: The formation of a workstream to specify chiplet physicals, the Chiplet Design eXchange



## Our Session: The making of an Open Interface

DJ/FB: Why do we care about chiplets and accelerators Steve/Achronix: How do we use chiplets – The PoC Mark/Avera: How do we wire chiplets together – BoW David/Intel: How do chiplets exchange bits – Link Layer Jawad/zGlue: How do we describe chiplets - CDX Wolfgang/Avera: How do package chiplets – Packaging Panel (Thursday): How do we work together on chiplets?



### Please Help! Join a Workstream

#### Join the PoC, Build fast:

(Quinn Jacobson/Jawad Nasrullah/ Jayaprakash Balachandran)

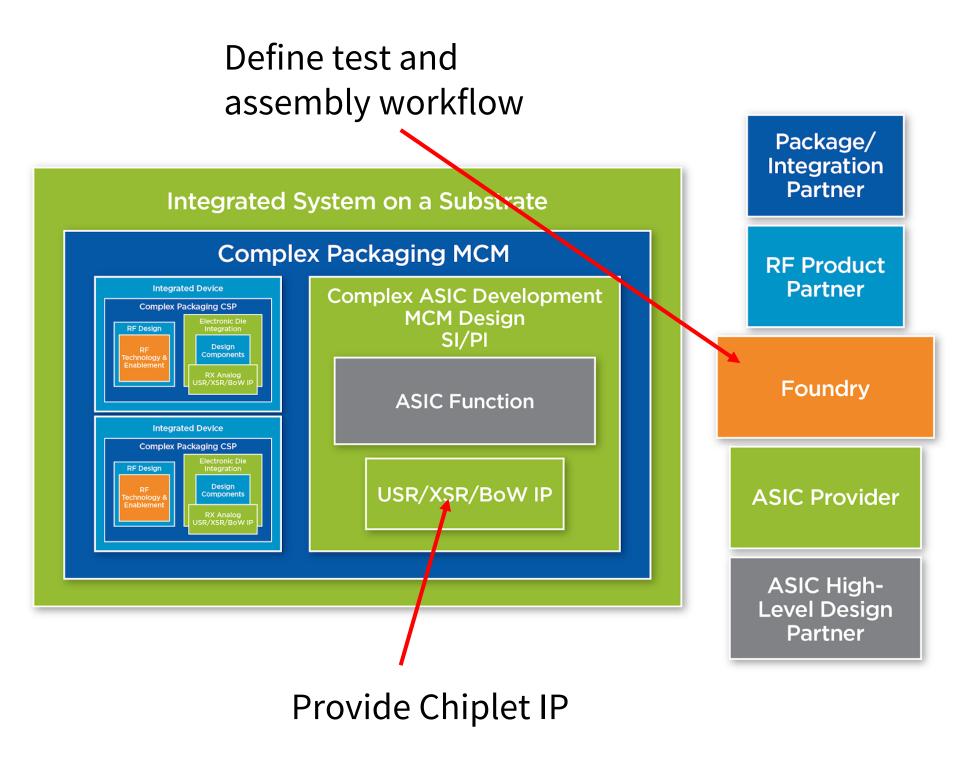
#### Join Interface/Standards:

(Mark Kuemerle/Ramin Farjad/ Robert Wang/David Kehlet)

#### Develop software Provide Cache Coherent Non-Coherent **ODSA** chiplets Intra-Chiplet Link Layer PCIe Link Layer BoW AIB, HBM, ORGANIC UBSTRATE Inter-chiplet PHY and packaging options Provide FPGA IP Define Develop **Architectural** Packaging + Interface **Provide PHY** Socket, Dev Board Technology

#### Join Business, IP and workflow:

(Sam Fuller/Dharmesh Jani)



Workstream contact information at the ODSA wiki



### Active Projects

| Project                   | Objective   | Organizations Participating  | Recent Results   | Upcoming Milestones                          | Needs  |
|---------------------------|---|--|--|--|--|
| PHY Analysis              | PHY requirements PHY analysis Cross-PHY abstraction (PIPE)                    | Alphawave, AnalogX,<br>Aquantia, Avera Semi,<br>Facebook, Intel, Kandou,<br>Netronome, zGlue,  | PHY Analysis paper<br>(published at Hot Interconnect)  | PIPE abstraction                             |  |
| BoW Interface             | No technology license fee, easy to port inter-chiplet interface spec          | Aquantia, Avera Semi,<br>Netronome   | BoW Interface proposal (published at Hot Interconnect) | BoW specification 0.7<br>End September, 2019 | Test chips, Chiplet library supporting interface           |
| Prototype                 | product that integrates existing die from multiple companies into one package | Achronix, Cisco, Netronome,<br>NXP, Samtec, Sarcina, zGlue,<br>Macom, Facebook   | Decomposable design flow.                              | Committed schedule                           | End user<br>End user participation<br>~30% funding is open |
| Chiplet design exchange   | Open chiplet physical description format.                                     | Ayar, NXP, zGlue,  | Draft spec   | ZEF Exchange format draft specification      |  |
| Link and Network<br>Layer | Interface and implementations – requirements and proposals                    | Achronix, Avera Semi, Intel,<br>Netronome, NXP, Xilinx   |  |  |  |
| Multi-chiplet test        | Test requirements for an open-chiplet interface                               | Engineers from: Achronix, AnalogX, ASE, Avera Semi, Ayar, Cisco, Facebook, Ferric, Intel, Kandou, Macom, Marvel, Netronome, NXP, On Semi, Samtec, Sarcina, Synopsys, Xilinx, zGlue |  |  |  |
| Chiplet monitoring        | Monitoring infrastructure for chiplet operation                               |  |  |  |  |
| Business workflow         | Formalize learnings from prototype effort                                     |  |  |  |  |

Wiki: <a href="https://www.opencompute.org/wiki/Server/ODSA">https://www.opencompute.org/wiki/Server/ODSA</a>, meet Fridays at 8 AM Pacific Time. Please join us.



